



The role of Additive Manufacturing (3D Printing) in e-mobility and electrification

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EOS Finland



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Content

- EOS
- EOS Metal Materials
- Some AM electification material considerations
- Case examples

EOS – Technology and Market Leader for 3D Printing Solutions



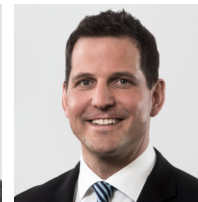
- **EOS** is the **world's leading technology** supplier in the field of **industrial 3D printing** of metals and polymers
- **Family-owned**, founded in 1989
- Headquartered in Krailling near **Munich**, Germany
- **Solution portfolio**: Additive Manufacturing (AM) systems, materials (plastics and metals), software, services and consulting
- Complete **end-to-end solutions**: from part design and data generation to part building and post-processing
- **EOS helps companies leverage competitive advantages in a variety of industries**, such as medical, aerospace, tooling, industry, lifestyle products and automotive



Marie Langer
CEO



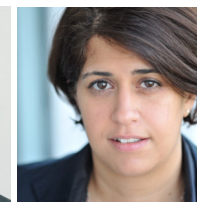
David Leigh
CTO



Nikolai Zaepernick
Life Cycle Solutions



Glynn Fletcher
Regions & USA



Ruha Reyhani
CTrO



Florian Mes
CPO

**EOS is committed to:
Innovation – Quality – Sustainability**



EOS Mission

EOS is the leading provider of Additive Manufacturing solutions. Our systems and services are essential to the digital factories of the future.

EOS Vision

Additive Manufacturing is a key technology for advanced industrial production.

EOS Metal Materials for Additive Manufacturing

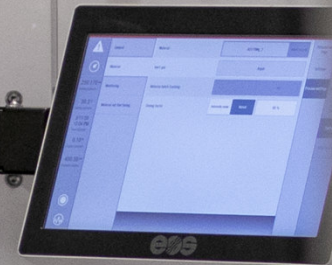


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Developing Metal materials and processes for EOS customers

Supporting EOS customers when metallurgical and analytical competences on metal powders, processes and material properties are needed



Competence Centre for Metals



Late 1980's

Development and metal powder
sourcing group of Electrolux
Rapid Development

Started as EOS development partner
Beginning of commercial DMLS
Joint development of materials and
processes for EOS metal AM systems

1994

2000

EOS Finland founded
General Manager Olli Nyrhilä

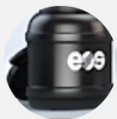
EOS Finland know-how and competence
has essential role in EOS metal
technology development
Personnel: ~65 employees (*> 35% in R&D*)

2021

Competence Centre for Metals



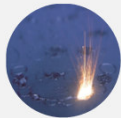
Development of
EOS metal powder products



Metal powder manufacturing



Global sourcing of metal powders



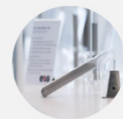
Development of EOS metal process
products for EOS metal systems

EOS Finland
has several
functions
within EOS

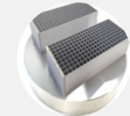
Customized materials & processes



Quality management,
powder & metallurgical analytics



Medical product competence



Regulatory affairs & compliance



EOS Metal Materials Portfolio



Aluminium	Cobalt Chrome	Nickel Alloy	Tool Steel	Stainless Steel	Engineering Steel	Titanium	Refractory Metal	Copper
EOS Aluminium AlSi10Mg	EOS CobaltChrome MP1	EOS NickelAlloy IN939	EOS MaragingSteel MS1	EOS StainlessSteel 316L	EOS CaseHardening-Steel 20MnCr5	EOS Titanium Ti64	EOS Tungsten W1	EOS Copper Cu
EOS Aluminium AlF357	EOS CobaltChrome RPD	EOS NickelAlloy IN718	EOS ToolSteel 1.2709	EOS StainlessSteel 316L VPro		EOS Titanium Ti64ELI		EOS Copper CuCP
	EOS CobaltChrome SP2	EOS NickelAlloy HX	EOS Stainless-Steel CX	EOS StainlessSteel 17-4PH		EOS Titanium TiCP Grade 2		EOS CopperAlloy CuCrZr
		EOS NickelAlloy IN625		EOS StainlessSteel PH1		EOS Titanium Ti64 Grade 5		
				EOS StainlessSteel GP1		EOS Titanium Ti64 Grade 23		
CUSTOMIZED OFFERING								
			EOS ToolSteel H13					EOS Bronze

EOS Finland machine park



In total over 20 EOS metal systems for research, development and constant re-qualification of EOS metal powders



1 EOS M400

2 EOS M400-4s



9 EOS M290s

Ti-alloy specific M290s and peripherals

Al-alloy specific M290 and peripherals

1 AMCM M290 1 kW

2 EOS M280s

1 EOS M270



5 EOS M100

EOS Finland machine park



- Several Melt Pool Monitoring and OT Monitoring units + non-released R&D hardware
- Furnaces for heat treatments in argon/nitrogen atmosphere
- Convection furnace for M4-platforms
- Vacuum furnace for M4-platforms
- EOS Laboratory with extensive capabilities for metallurgical and powder analysis



We are
experts in
metal AM
technology

E-mobility and electrification requires high electrical conductivity



Some general considerations about electrical conductivity and AM

- Grain size effect on strength properties
 - Very small grain size of AM allows for less alloying for same mechanical performance as conventionally manufactured materials.
- Heat treatments can be used to improve on conductivity as well as other properties.
- High alloying typically leads to better mechanical properties but also poor conductivity
- Surface conductivity in antenna applications can be optimized by parametrizing surfaces to have high density, while center of piece can be replaced with more porous bulk or lattice structure
 - Lightweighting for lower transportation and operating costs in space applications

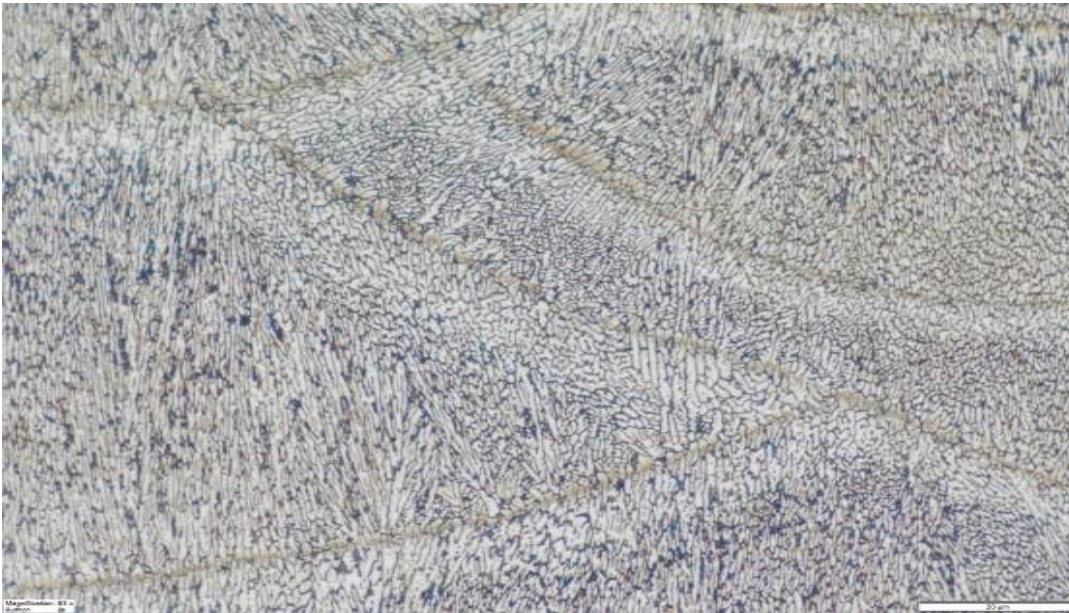
Orientation dependency of external properties



Laser melting process comprises of extremely fast melting and re-solidification.

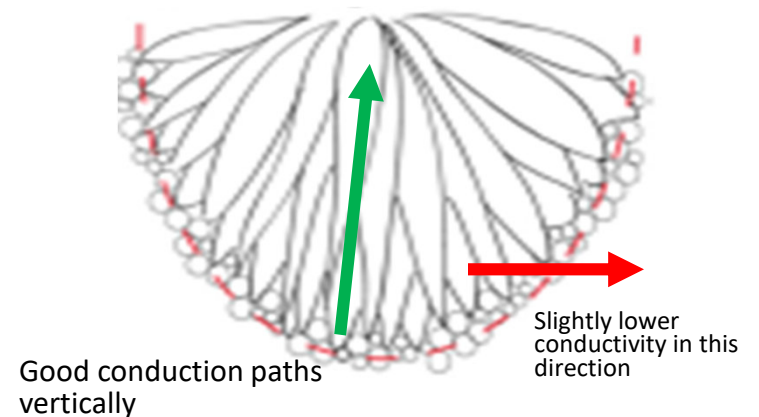
Due to the layerwise manufacturing method, the parts exhibit anisotropic properties depending strongly on the building direction. This is especially seen in mechanical properties, but other properties such as conductivity have dependency on build direction, too.

With heat treatment – more uniform microstructure and less orientation dependency can be gained.

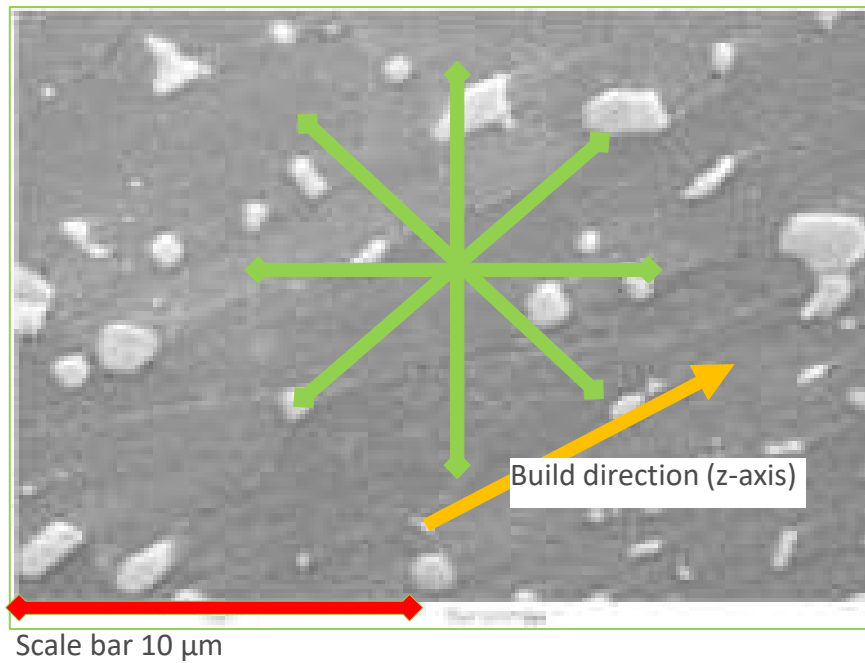


Al F357 alloy (as built), etched with Groesbeck's reagent. Scale bar is 20 µm.

Underlying aluminium grain structure that is found under silicon network



Same structure after heat treatment (SEM image)



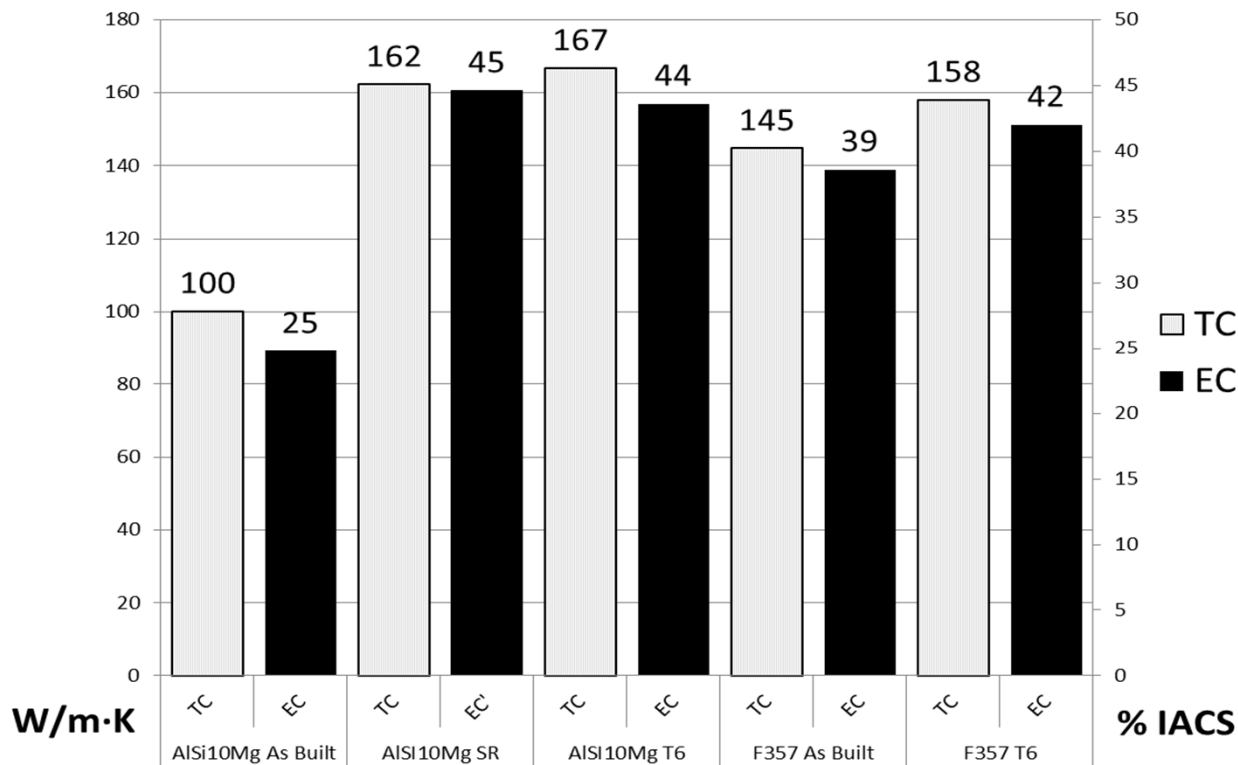
Improved and more uniform conductivity in all directions after heat treatment thanks to microstructural changes

Spheroidization and break-up of silicon network leads to more free path for electronic conduction and reduces alloy supersaturation.

ALSi10Mg and F357/ALSi7Mg Aluminium Conductivity



Thermal conductivity (TC) vs. electrical conductivity (EC)



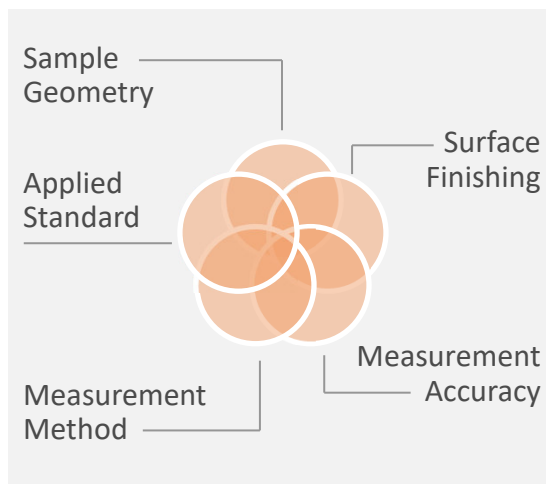
Strong correlation between thermal conductivity (TC) values and electrical conductivity (EC) values in

Stress relief and T6 heat treatments improve on conductivity when supersaturation of alloying is relieved through precipitate formation.

*IACS International Annealed Copper Standard, where scale value of 100 %IACS represents electrical conductivity of commercially pure copper.

Thermal Conductivity of Additively Manufactured Thermal Management Components.
Jukka Simola. EOS Finland Oy.
EuroPM2019, MECC Maastricht, October 15th 2019

In electrical applications Conductivity is Key – and also the Challenge



Electrical

Resistance (U/I)

Volume resistivity (Ωm) at ref. T t_0

Conductivity (S/m)

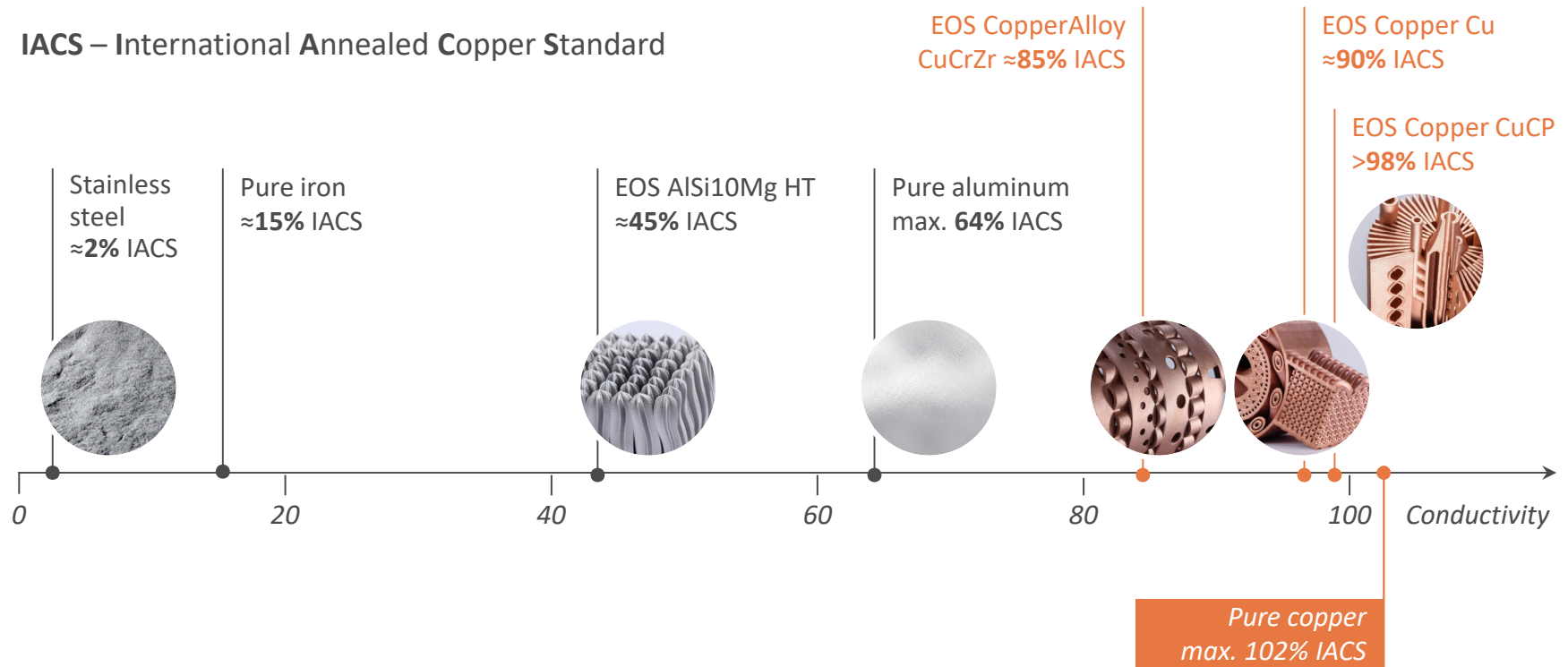
Conductivity (% IACS)

At EOS: Eddy current electrical conductivity measurement (ASTM E1004 – 17)

Conductivity is Key – and also the Challenge



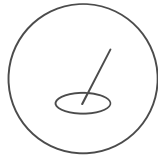
IACS – International Annealed Copper Standard



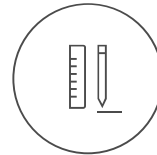
Challenges with Conductivity



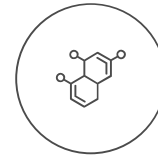
*Heat escaping from
the melting process*



Melt pool size

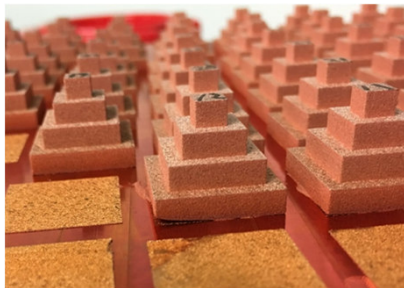


*Part & support
design*

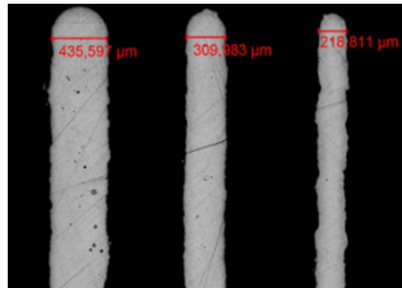
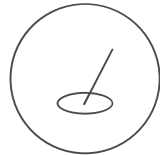


Oxidation

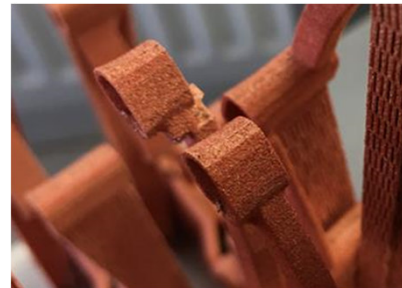
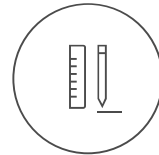
Challenges with Conductivity



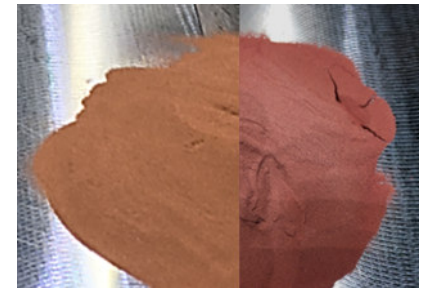
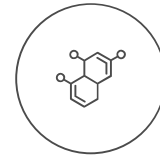
Heat can build up in specific areas and escape in other areas



Part precision control needs special attention

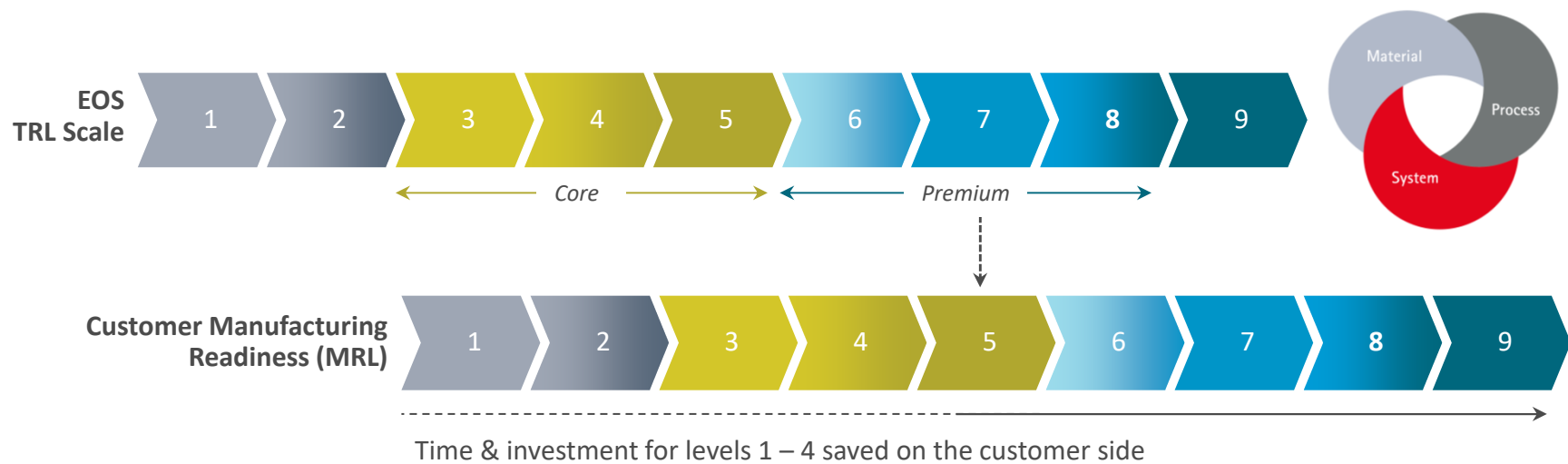


System robustness & precision is highlighted



Oxidation leads to discoloration – a natural tendency for copper – but not critical

EOS Technology Readiness Levels Translate to Manufacturing Readiness Levels

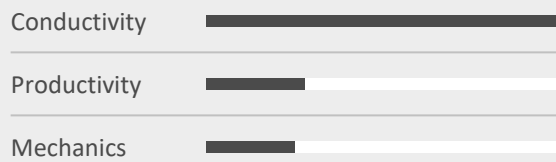


EOS copper solutions are at TRL 3, work is in progress to advance them to higher levels

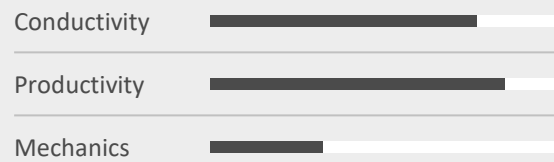
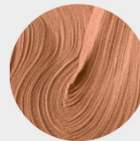
Different Copper Alloys for Different Applications



Pure Copper



CuCrZr



CuNi2SiCr

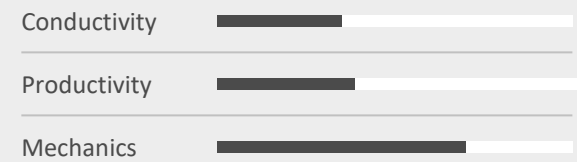


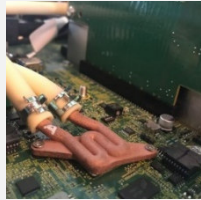
Image sources: 3druck.com on Protig; for Launcher engine AMCM; antenna from Polymertal; Cooler by Cloud & Heat, AM Metals; Cooler by Stratasys Direct Manufacturing; stator by AM Metals; CuNi Cooler by Modelltechnik and AM Metals; Kjellberg Finsterwalde with AM Metals;

First Applications Commercialized using DMLS® Technology



Coolers / Heat Exchangers

- Low leakage risk
- Miniaturization



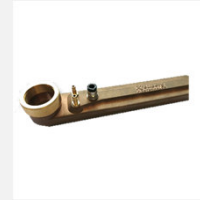
Electric Motors

- Smaller series
- Higher energy densities



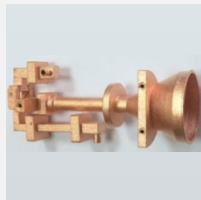
Nozzles

- Optimized flow
- Longer lifetime



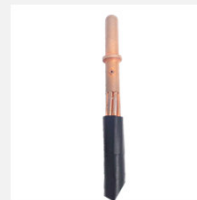
Antennas / RF Communication

- Miniaturization
- High efficiency



Electrical Contacts

- Higher currents
- Integrated active cooling



Inductors

- Customization
- Digital production chain

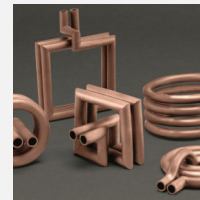


Image sources l.t.r.: Cloud & Heat – built by AM Metals; AM Metals; AM Metals; Polymertal; Kellberg Finsterwalde and AM Metals; Protiq, a Phoenix Contact Company, press release with EOS;

Pure Copper: Performance Increase up to 45%



- Start-up for electric motor production by additive manufacturing
- Lot size 1 for fast prototyping
- Large serials for improved performance



3D printed hair pin “winding” for traction motor

CuCrZr – Collaborating for Success



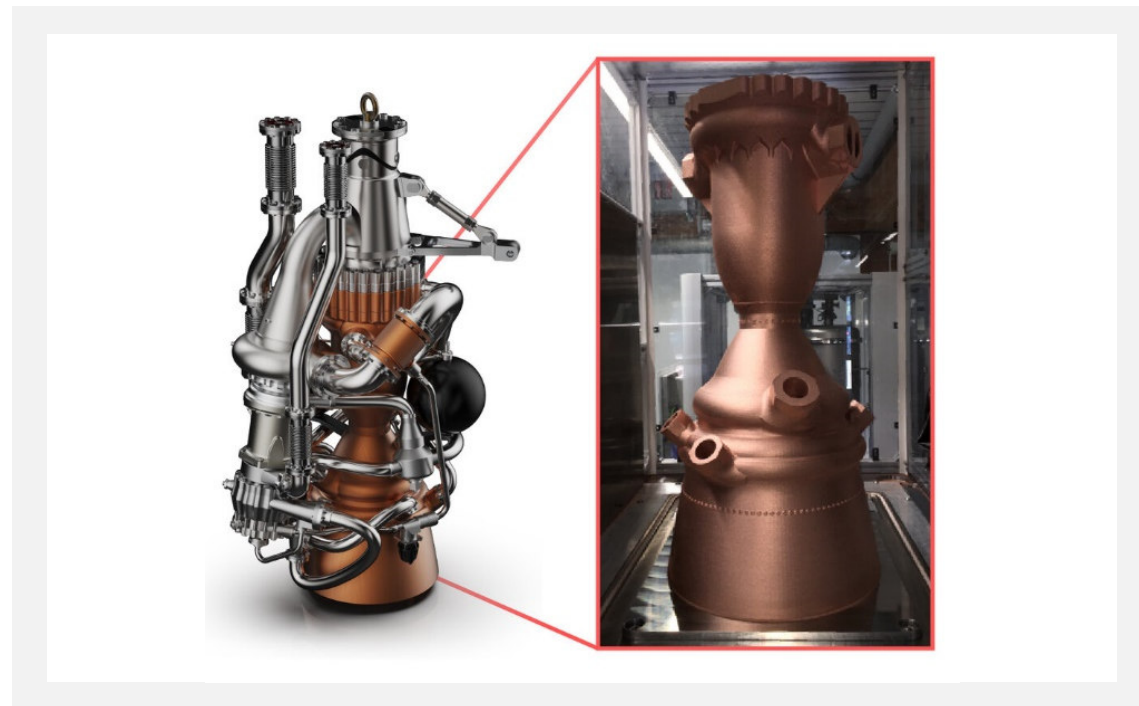
LAUNCHER

launcherspace.com

LAUNCHER E-2

3T

AMEM

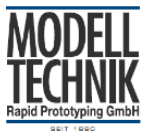


CuNi2SiCr: Cooler in Serial Production



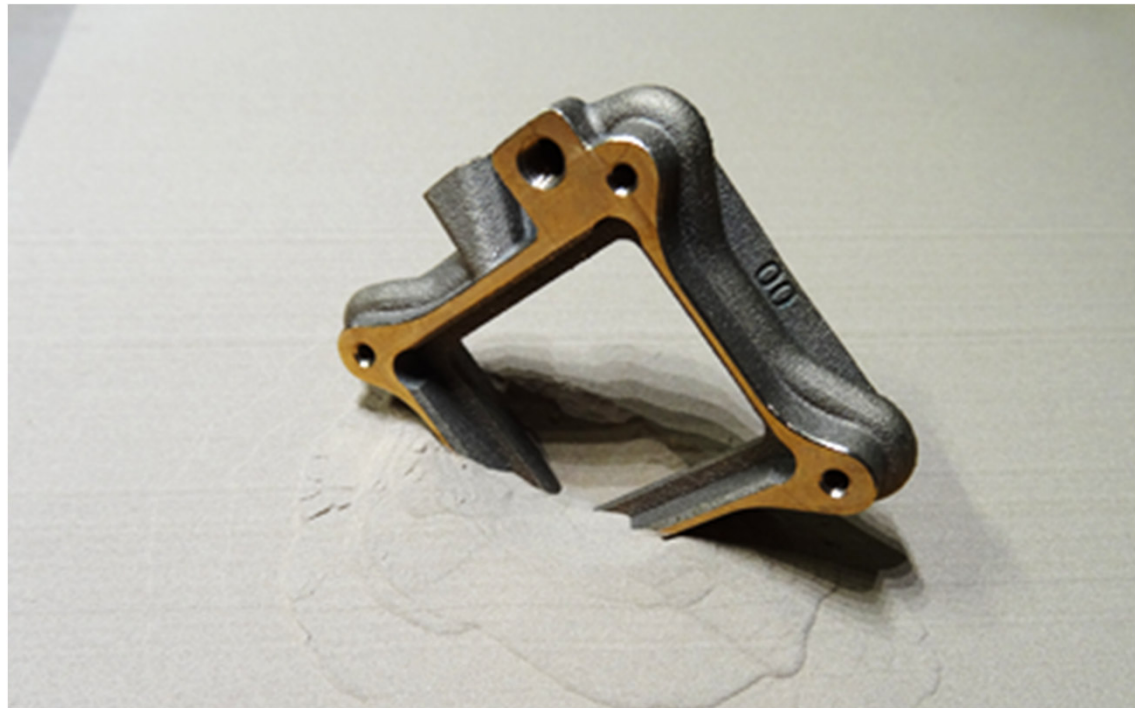
- Made for medical devices and without weld seams
- Less scrap by solving the leakage problem
- Better cooling by factor 3
- Simplified assembly and better economics

production by



engineering by

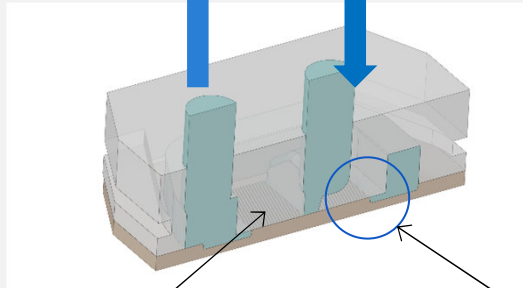
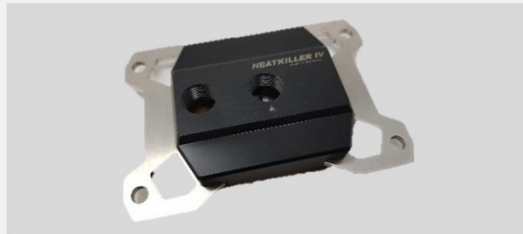
AM METALS



Source: ModellTechnik Rapid Prototyping GmbH

Innovating a Gaming CPU Cooler with 3D Printing

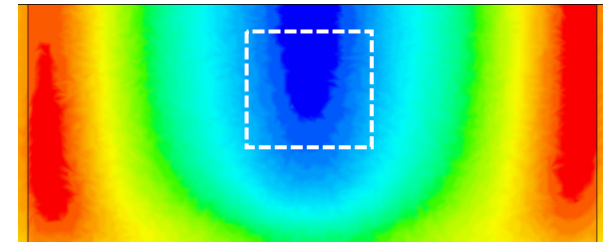
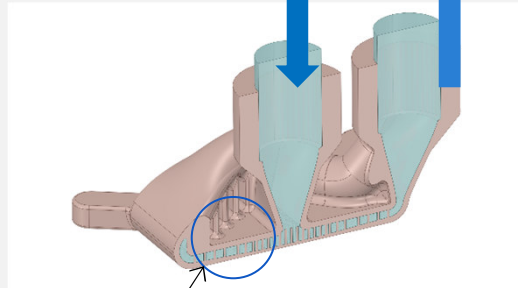
Conventional Design



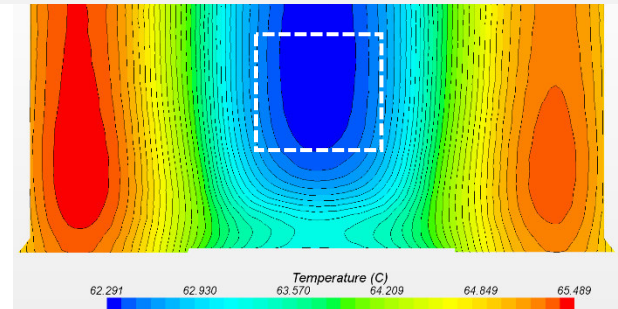
0.3mm
Fin

Impingement
cooling

AM Design



Temperature distribution on base plate (Conventional Design)



Temperature distribution on base plate (AM Design)

New EOS alloy types under development

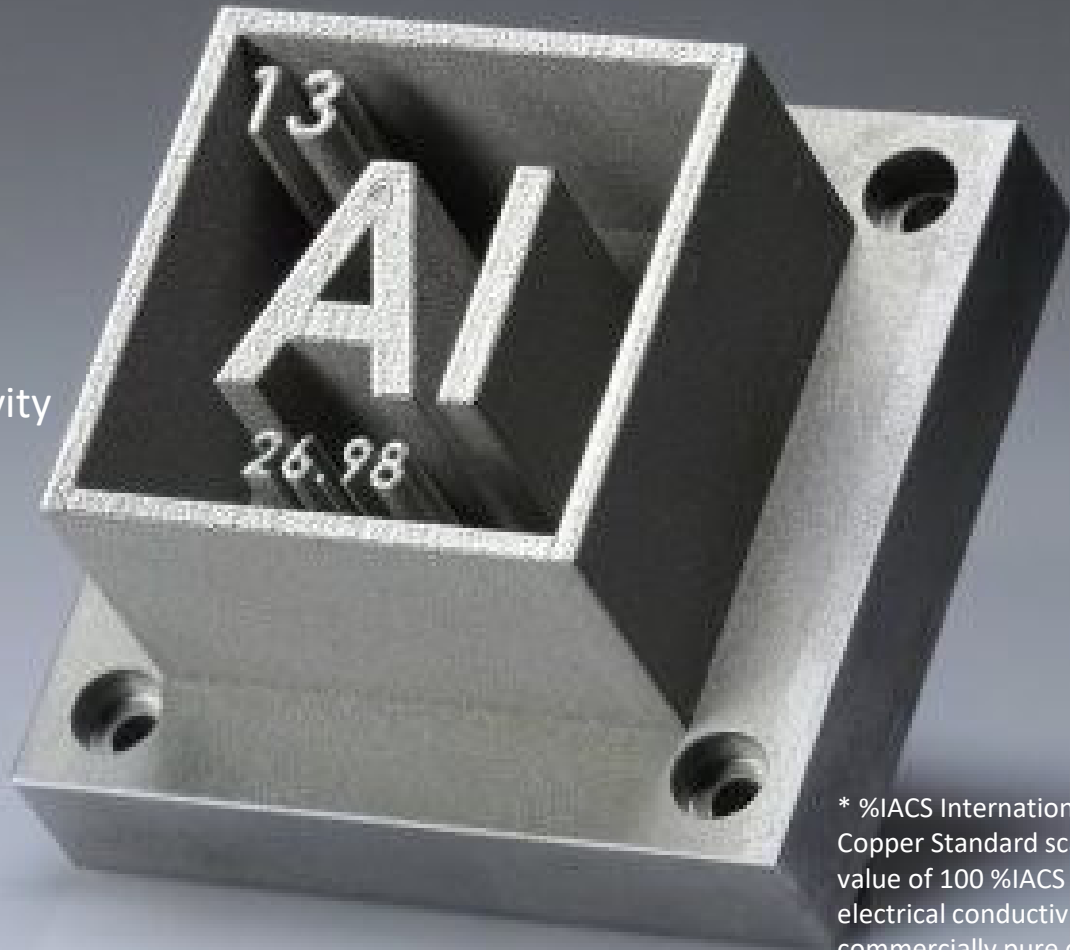
1) EOS High purity aluminium

$RP_{0.2}$ ~65 MPa, up to 62 %IACS electrical conductivity, thermal conductivity up to 230 W/mK

2) EOS Low alloy, high conductivity aluminium,

$RP_{0.2}$ 150 MPa, electrical conductivity up to 50-53 %IACS, thermal conductivity 195-205 W/mK

Designed for waveguides for telecommunication, thermal management components, electronics casings etc.



* %IACS International Annealed Copper Standard scale, where value of 100 %IACS represents electrical conductivity of commercially pure copper.



Thank you!

EOS®, Alumide®, AMQ®, CarbonMide®, DirectMetal®, DMLS®, e-Manufacturing®, EOSAME®, EOSINT®, EOSIZE®, EOSPACE®, EOSPRINT®, EOSTATE®, EOSTYLE®, FORMIGA®, PrimeCast® and PrimePart® are registered trademarks of EOS GmbH in some countries. For more information visit www.eos.info/trademarks.

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